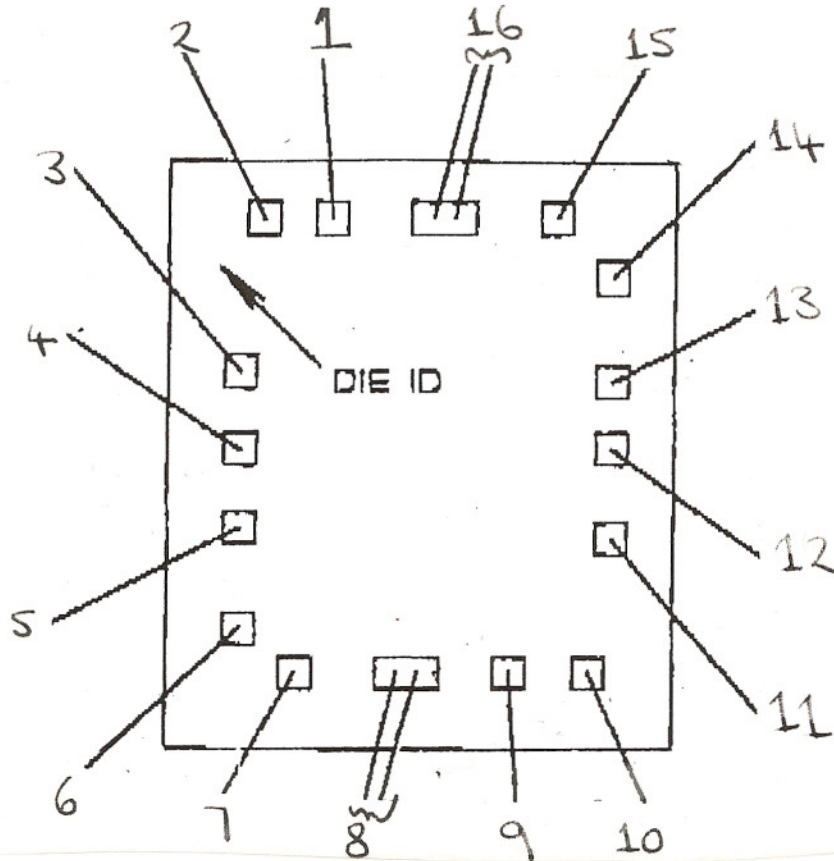




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad Function

1	INPUT A
2	OUTPUT A2
3	OUTPUT A1
4	ENABLE
5	OUTPUT B1
6	OUTPUT B2
7	INPUT B
8	GND
9	INPUT C
10	OUTPUT C2
11	OUTPUT C1
12	ENABLE
13	OUTPUT D1
14	OUTPUT D2
15	INPUT D
16	VCC

Topside Metal: Al (Aluminum)

Backside:

Backside Potential: Ground

Mask Ref:

Bond Pads (Mils): 4 x 4

APPROVED BY:

MFG: National



DIE SIZE (Mils): 74 x 64

THICKNESS: 15

DATE: 4/28/99

P/N: DS26C31